

LM48312 Boomer[™] Audio Power Amplifier Series 2.6W, Ultra-Low EMI, Filterless, Mono Class D Audio Power Amplifier with E²S

Check for Samples: LM48312

FEATURES

- Passes FCC Class B Radiated Emissions with 20 Inches of Cable
- E²S System Reduces EMI While Preserving Audio Quality and Efficiency
- Output Short Circuit Protection with Auto-Recovery
- No Output Filter Required
- Improved Audio Quality
- Minimum External Components
- Five Logic Selectable Gain Settings (0, 3, 6, 9, 12dB)
- Low Power Shutdown Mode
- Click and Pop Suppression
- Available in Space-Saving DSBGA Package

APPLICATIONS

- Mobile Phones
- PDAs
- Laptops

KEY SPECIFICATIONS

- Efficiency at 3.6V, 400mW into 8Ω, 84% (Typ)
- Efficiency at 5V, 1W into 8Ω, 88% (Typ)
- Quiescent Power Supply Current at 5V, 3.1mA
- Power Output at $V_{DD} = 5V$, $R_L = 4\Omega$
 - THD+N ≤ 10%, 2.6W (Typ)
 - THD+N ≤ 1%, 2.1W (Typ)
- Power Output at V_{DD} = 5V, R_L = 8Ω
 - THD+N ≤ 10%, 1.6W (Typ)
 - THD+N ≤ 1%, 1.3W (Typ)
- Shutdown Current, 0.01µA (Typ)

DESCRIPTION

The LM48312 is a single supply, high efficiency, mono, 2.6W, filterless switching audio amplifier. The LM48312 features Tl's Enhanced Emissions Suppression (E²S) system, that features a unique patented ultra low EMI, spread spectrum, PWM architecture, that significantly reduces RF emissions while preserving audio quality and efficiency. The E²S system improves battery life, reduces external component count, board area consumption, and system cost, simplifying design.

The LM48312 is designed to meet the demands of portable multimedia devices. Operating from a single 5V supply, the device is capable of delivering 2.6W of continuous output power to a 4Ω load with less than 10% THD+N. Flexible power supply requirements allow operation from 2.4V to 5.5V. The LM48312 features both a spread spectrum modulation scheme, and an advanced, patented edge rate control (ERC) architecture that significantly reduces emissions, while maintaining high quality audio reproduction (THD+N = 0.03%) and high efficiency (η = 88%).

The LM48312 features high efficiency compared to conventional Class AB amplifiers, and other low EMI Class D amplifiers. When driving an 8Ω speaker from a 5V supply, the device operates with 88% efficiency at $P_O=1W$. The LM48312 features five gain settings, selected through a single logic input, further reducing solution size. A low power shutdown mode reduces supply current consumption to $0.01\mu A$.

Advanced output short circuit protection with autorecovery prevents the device from being damaged during fault conditions. Superior click and pop suppression eliminates audible transients on powerup/down and during shutdown.

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Typical Application

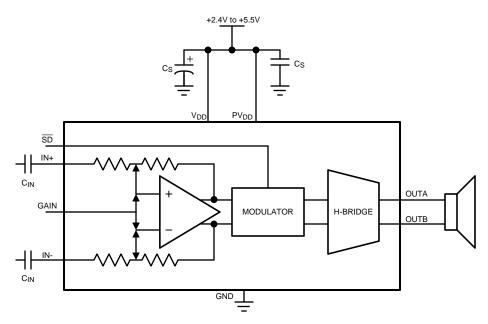


Figure 1. Typical Audio Amplifier Application Circuit

Connection Diagram

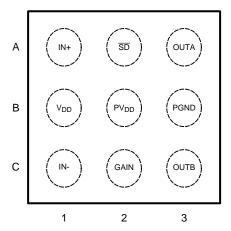


Figure 2. DSBGA Package 1.539mm x 1.565mm x 0.6mm Top View See Package Number YZR0009



BUMP DESCRIPTION

Pin	Name	Description
A1	IN+	Non-Inverting Input
A2	SD	Active Low Shutdown Input. Connect to V _{DD} for normal operation.
A3	OUTA	Non-Inverting Output
B1	V_{DD}	Power Supply
B2	PV_{DD}	H-Bridge Power Supply
В3	PGND	Ground
C1	IN-	Inverting Input
C2	GAIN	Gain Select: $GAIN = FLOAT: A_V = 0dB$ $GAIN = V_{DD}: A_V = 3dB$ $GAIN = GND: A_V = 6dB$ $GAIN = 20k\Omega \text{ to } GND = 9dB$ $GAIN = 20k\Omega \text{ to } V_{DD} = 12dB$
C3	OUTB	Inverting Output



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

Absolute Maximum Ratings (1)(2)(3)

	.9-					
Supply Voltage		6.0V				
Storage Temperature		−65°C to +150°C				
Input Voltage	nput Voltage					
Power Dissipation (4)	Internally Limited					
ESD Rating ⁽⁵⁾	2000V					
ESD Rating ⁽⁶⁾	200V					
Junction Temperature		150°C				
Thermal Resistance	θ_{JA}	70°C/W				
Soldering Information						
See AN-1112 (SNVA009) "DSBGA	Wafer Level Chip Scale Pack	age."				

- (1) "Absolute Maximum Ratings" indicate limits beyond which damage to the device may occur, including inoperability and degradation of device reliability and/or performance. Functional operation of the device and/or non-degradation at the Absolute Maximum Ratings or other conditions beyond those indicated in the Recommended Operating Conditions is not implied. The Recommended Operating Conditionsindicate conditions at which the device is functional and the device should not be operated beyond such conditions. All voltages are measured with respect to the ground pin, unless otherwise specified.
- (2) The Electrical Characteristics tables list ensured specifications under the listed Recommended Operating Conditions except as otherwise modified or specified by the Electrical Characteristics Conditions and/or Notes. Typical specifications are estimations only and are not ensured.
- (3) If Military/Aerospace specified devices are required, please contact the Texas Instruments Sales Office/Distributors for availability and specifications.
- (4) The maximum power dissipation must be derated at elevated temperatures and is dictated by T_{JMAX}, θ_{JA}, and the ambient temperature, T_A. The maximum allowable power dissipation is P_{DMAX} = (T_{JMAX} T_A) / θ_{JA} or the number given in Absolute Maximum Ratings, whichever is lower.
- (5) Human body model, applicable std. JESD22-A114C.
- (6) Machine model, applicable std. JESD22-A115-A.

Operating Ratings⁽¹⁾⁽²⁾

Temperature Range	$T_{MIN} \le T_A \le T_{MAX}$	-40°C ≤ T _A ≤ +85°C
	Supply Voltage (V _{DD} , PV _{DD})	$2.4V \le V_{DD} \le 5.5V$

- (1) "Absolute Maximum Ratings" indicate limits beyond which damage to the device may occur, including inoperability and degradation of device reliability and/or performance. Functional operation of the device and/or non-degradation at the Absolute Maximum Ratings or other conditions beyond those indicated in the Recommended Operating Conditions is not implied. The Recommended Operating Conditionsindicate conditions at which the device is functional and the device should not be operated beyond such conditions. All voltages are measured with respect to the ground pin, unless otherwise specified.
- (2) The Electrical Characteristics tables list ensured specifications under the listed Recommended Operating Conditions except as otherwise modified or specified by the Electrical Characteristics Conditions and/or Notes. Typical specifications are estimations only and are not ensured.



Electrical Characteristics $V_{DD} = PV_{DD} = 5V^{(1)(2)}$

The following specifications apply for $A_V = 6dB$, $R_1 = 8\Omega$, f = 1kHz, unless otherwise specified. Limits apply for $T_A = 25^{\circ}C$

Symbol				Units			
Symbol V _{DD}	Parameter	Conditions	Min (3)	Typ (4)	Max (3)	(Limits)	
V_{DD}	Supply Voltage Range		2.4		5.5	V	
DD	Quiescent Power Supply Current	$V_{IN} = 0, R_L = 8\Omega$ $V_{DD} = 3.3V$ $V_{DD} = 5V$		2.6 3.1	3.3 3.9	mA mA	
SD	Shutdown Current	Shutdown enabled		0.01	1.0	μA	
V _{os}	Differential Output Offset Voltage	$V_{IN} = 0$	-48	10	48	mV	
√ _{IH}	Logic Input High Voltage		1.4			V	
√ _{IL}	Logic Input Low Voltage				0.4	V	
Γ _{WU}	Wake Up Time			7.5		ms	
: SW	Switching Frequency			300±30		kHz	
A _V	Gain	GAIN = FLOAT GAIN = V_{DD} GAIN = GND GAIN = $20k\Omega$ to GND GAIN = $20k\Omega$ to V_{DD}	-0.5 2.5 5.5 8.5 11.5	0 3 6 9 12	0.5 3.5 6.5 9.5 12.5	dB dB dB dB dB	
R _{IN}	Input Resistance	$A_V = 0dB$ $A_V = 3dB$ $A_V = 6dB$ $A_V = 9dB$ $A_V = 12dB$	20	56 49 42 35 27		kΩ kΩ kΩ kΩ	
		$R_L = 4\Omega$, THD = 10% f = 1kHz, 22kHz BW $V_{DD} = 5V$ $V_{DD} = 3.3V$ $V_{DD} = 2.5V$ $R_1 = 8\Omega$, THD = 10%		2.6 1.1 580		W W mW	
D	Out-of Provide	f = 1kHz, 22kHz BW V _{DD} = 5V V _{DD} = 3.3V V _{DD} = 2.5V		1.6 660 354		W mW mW	
P _O	Output Power	$R_{L} = 4\Omega$, THD = 1% f = 1kHz, 22kHz BW $V_{DD} = 5V$ $V_{DD} = 3.3V$ $V_{DD} = 2.5V$		2.1 900 460		W mW mW	
		$R_{L} = 8\Omega$, THD = 1% f = 1 kHz, 22kHz BW $V_{DD} = 5 \text{V}$ $V_{DD} = 3.3 \text{V}$ $V_{DD} = 2.5 \text{V}$	1.1 450	1.3 530 286		W (min) mW mW	
THD+N	Total Harmonic Distortion + Noise	$P_O = 200$ mW, $R_L = 8\Omega$, $f = 1$ kHz		0.027		%	
או+טווו	Total Harmonic Distortion + Noise	$P_O = 100$ mW, $R_L = 8\Omega$, $f = 1$ kHz		0.03		%	
PSRR	Power Supply Rejection Ratio	$V_{RIPPLE} = 200 \text{mV}_{P-P} \text{ Sine,}$ Inputs AC GND, $A_V = 0 \text{dB,}$ $C_{IN} = 1 \mu \text{F}$ $f_{RIPPLE} = 217 \text{Hz}$ $f_{RIPPLE} = 1 \text{kHz}$		71 70		dB dB	
CMRR	Common Mode Rejection Ratio	$V_{RIPPLE} = 1V_{P-P}$, $f_{RIPPLE} = 217Hz$ $A_V = 0dB$		65		dB	

⁽¹⁾ The *Electrical Characteristics* tables list ensured specifications under the listed *Recommended Operating Conditions* except as otherwise modified or specified by the *Electrical Characteristics Conditions* and/or Notes. Typical specifications are estimations only and are not ensured.

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⁽²⁾ R_L is a resistive load in series with two inductors to simulate an actual speaker load. For $R_L = 8\Omega$, the load is $15\mu H + 8\Omega$, $+15\mu H$. For R_L = 4Ω , the load is 15μ H + 4Ω + 15μ H.

 ⁽³⁾ Datasheet min/max specification limits are specified by test or statistical analysis.
 (4) Typical values represent most likely parametric norms at T_A = +25°C, and at the *Recommended Operation Conditions* at the time of product characterization and are not ensured.



Electrical Characteristics $V_{DD} = PV_{DD} = 5V^{(1)(2)}$ (continued)

The following specifications apply for $A_V = 6dB$, $R_L = 8\Omega$, f = 1kHz, unless otherwise specified. Limits apply for $T_A = 25^{\circ}C$.

Symbol				Units		
	Parameter	Conditions	Min Typ Ma. (3) (3)		Max (3)	(Limits)
η	Efficiency	V_{DD} = 5V, P_{OUT} = 1W V_{DD} = 3.3V, P_{OUT} = 400mW		88 85		% %
SNR	Signal to Noise Ratio	P _O = 1W		95		dB
CMVR	Common Mode Input Voltage Range		0	V _{DD} - 0.25		V
ε _{OS}	Output Noise	Un-weighted, $A_V = 0dB$ A-weighted, $A_V = 0dB$		69 48		μV μV

Test Circuits

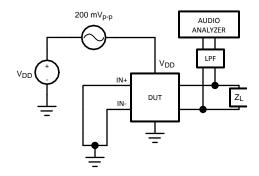


Figure 3. PSRR Test Circuit

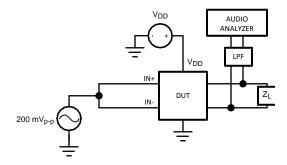


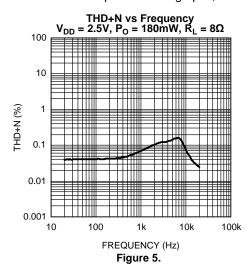
Figure 4. CMRR Test Circuit

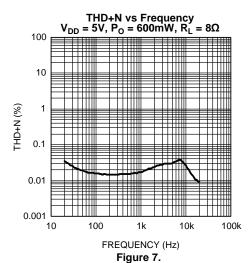
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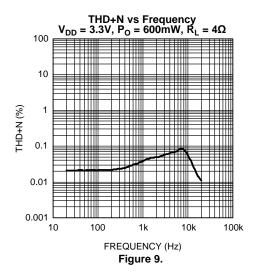


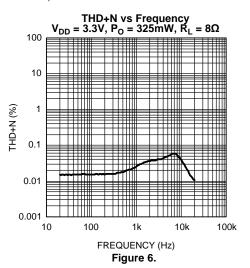
Typical Performance Characteristics

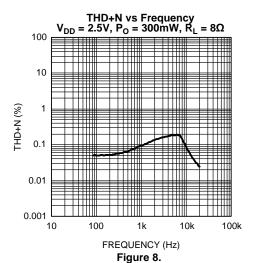
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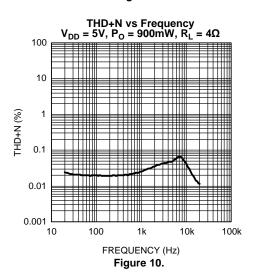






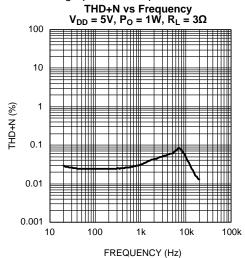


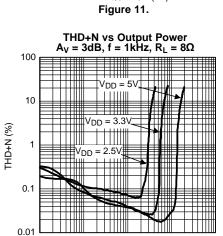






For all performance graphs, the Output Gains are set to 0dB, unless otherwise noted.

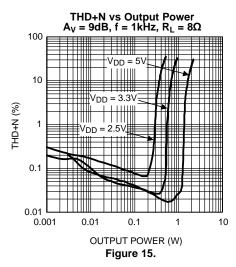




OUTPUT POWER (W) Figure 13.

10

0.1



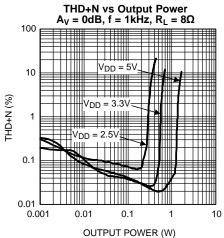
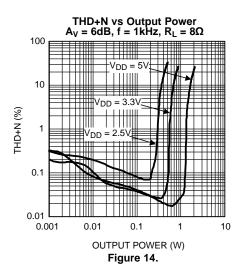


Figure 12.



THD+N vs Output Power $A_V = 12dB$, f = 1kHz, $R_L = 8\Omega$ 100 10 THD+N (%) 0.1

0.01

0.001

OUTPUT POWER (W) Figure 16.

0.1

0.01

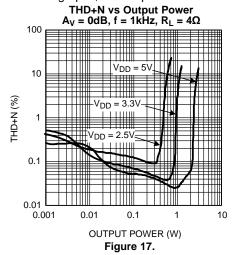
10

0.001

0.01



For all performance graphs, the Output Gains are set to 0dB, unless otherwise noted.



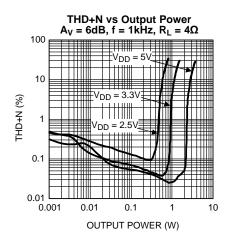
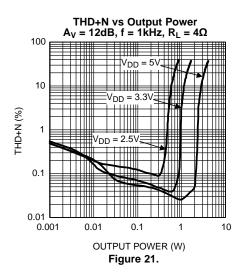
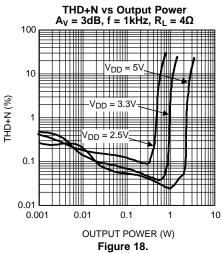
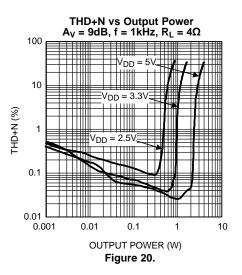
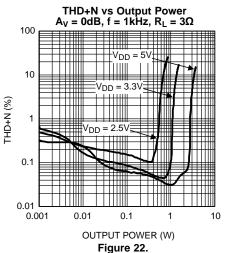


Figure 19.



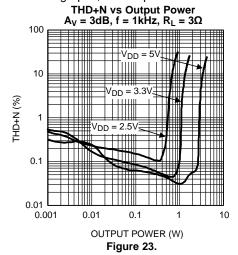


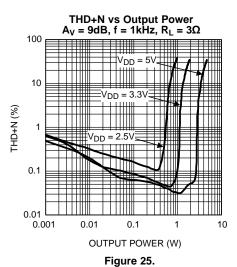


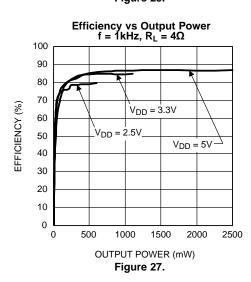


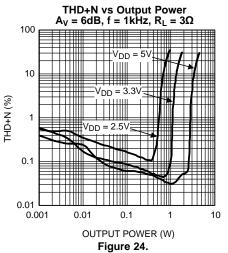


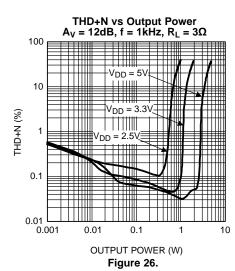
For all performance graphs, the Output Gains are set to 0dB, unless otherwise noted.

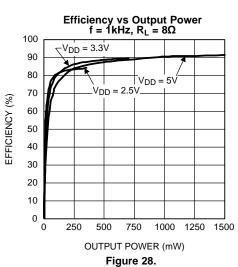






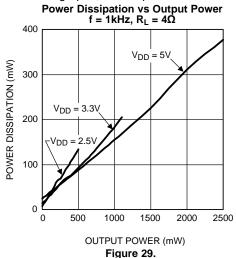








For all performance graphs, the Output Gains are set to 0dB, unless otherwise noted.





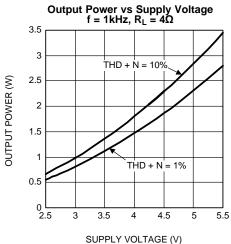
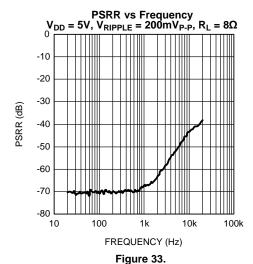


Figure 31.



Power Dissipation vs Output Power $f=1kHz,\,R_L=8\Omega$

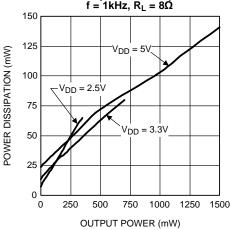


Figure 30.

Output Power vs Supply Voltage $f = 1kHz, R_L = 8\Omega$

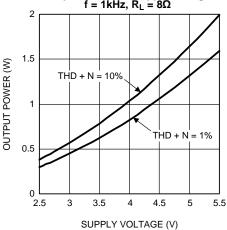


Figure 32.

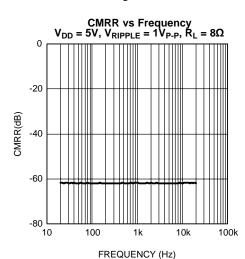
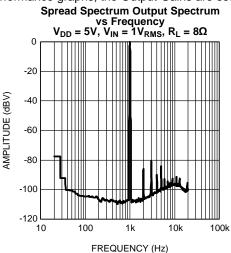


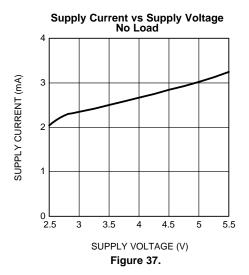
Figure 34.

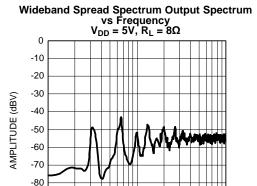


For all performance graphs, the Output Gains are set to 0dB, unless otherwise noted.









FREQUENCY (Hz) Figure 36.

1k

10k

-90 -100

100

Shutdown Supply Current vs Supply Voltage No Load

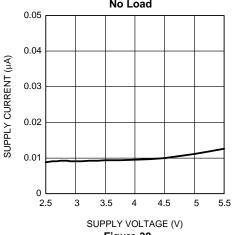


Figure 38.



APPLICATION INFORMATION

GENERAL AMPLIFIER FUNCTION

The LM48312 mono Class D audio power amplifier features a filterless modulation scheme that reduces external component count, conserving board space and reducing system cost. The outputs of the device transition from V_{DD} to GND with a 300kHz switching frequency. With no signal applied, the outputs (V_{OUTA} and V_{OUTB}) switch with a 50% duty cycle, in phase, causing the two outputs to cancel. This cancellation results in no net voltage across the speaker, thus there is no current to the load in the idle state.

With the input signal applied, the duty cycle (pulse width) of the LM48312 outputs changes. For increasing output voltage, the duty cycle of V_{OUTB} increases, while the duty cycle of V_{OUTB} decreases. For decreasing output voltages, the converse occurs. The difference between the two pulse widths yields the differential output voltage.

ENHANCED EMISSIONS SUPPRESSION SYSTEM (E²S)

The LM48312 features TI's patented E²S system that reduces EMI, while maintaining high quality audio reproduction and efficiency. The E²S system features spread spectrum and advanced edge rate control (ERC). The LM48312 ERC greatly reduces the high frequency components of the output square waves by controlling the output rise and fall times, slowing the transitions to reduce RF emissions, while maximizing THD+N and efficiency performance. The overall result of the E²S system is a filterless Class D amplifier that passes FCC Class B radiated emissions standards with 20in of twisted pair cable, with excellent 0.03% THD+N and high 88% efficiency.

SPREAD SPECTRUM

The spread spectrum modulation reduces the need for output filters, ferrite beads or chokes. The switching frequency varies randomly by 30% about a 300kHz center frequency, reducing the wideband spectral contend, improving EMI emissions radiated by the speaker and associated cables and traces. Where a fixed frequency class D exhibits large amounts of spectral energy at multiples of the switching frequency, the spread spectrum architecture of the LM48312 spreads that energy over a larger bandwidth (See Typical Performance Characteristics). The cycle-to-cycle variation of the switching period does not affect the audio reproduction, efficiency, or PSRR.

DIFFERENTIAL AMPLIFIER EXPLANATION

As logic supplies continue to shrink, system designers are increasingly turning to differential analog signal handling to preserve signal to noise ratios with restricted voltage signs. The LM48312 features a fully differential speaker amplifier. A differential amplifier amplifies the difference between the two input signals. Traditional audio power amplifiers have typically offered only single-ended inputs resulting in a 6dB reduction of SNR relative to differential inputs. The LM48312 also offers the possibility of DC input coupling which eliminates the input coupling capacitors. A major benefit of the fully differential amplifier is the improved common mode rejection ratio (CMRR) over single ended input amplifiers. The increased CMRR of the differential amplifier reduces sensitivity to ground offset related noise injection, especially important in noisy systems.

POWER DISSIPATION AND EFFICIENCY

The major benefit of a Class D amplifier is increased efficiency versus a Class AB. The efficiency of the LM48312 is attributed to the region of operation of the transistors in the output stage. The Class D output stage acts as current steering switches, consuming negligible amounts of power compared to their Class AB counterparts. Most of the power loss associated with the output stage is due to the IR loss of the MOSFET onresistance, along with switching losses due to gate charge.

GAIN SETTING

The LM48312 features five internally configured gain settings, 0, 3, 6, 9, and 12dB. The device gain is selected through a single pin (GAIN). The gain settings are shown in Table 1. The gain of the LM48312 is determined at startup. When the LM48312 is powered up or brought out of shutdown, the device checks the state of GAIN, and sets the amplifier gain accordingly. Once the gain is set, the state of GAIN is ignored and the device gain cannot be changed until the device is either shutdown or powered down.



Table 1. Gain Setting

GAIN	GAIN SETTING
FLOAT	0dB
V_{DD}	3dB
GND	6dB
20kΩ to GND	9dB
20 k Ω to V_{DD}	12dB

For proper gain selection:

- 1. Use $20k\Omega$ resistors with 10% tolerance or better for the 9dB and 12dB gain settings.
- 2. Short GAIN to either V_{DD} or GND through 100 Ω or less for the 3dB and 6dB gain settings.
- 3. FLOAT = $20M\Omega$ or more for the 0dB gain setting.

SHUTDOWN FUNCTION

The LM48312 features a low current shutdown mode. Set $\overline{SD} = GND$ to disable the amplifier and reduce supply current to $0.01\mu A$.

Switch \overline{SD} between GND and V_{DD} for minimum current consumption is shutdown. The LM48312 may be disabled with shutdown voltages in between GND and V_{DD} , the idle current will be greater than the typical 0.1µA value. Increased THD+N may also be observed when a voltage of less than V_{DD} is applied to \overline{SD} .

The LM48312 shutdown input <u>has</u> and internal pulldown resistor. The purpose of this resistor is to eliminate any unwanted state changes when SD is floating. To minimize shutdown current, SD should be driven to GND or left floating. If SD is not driven to GND or floating, an increase in shutdown supply current will be noticed.

PROPER SELECTION OF EXTERNAL COMPONENTS

Audio Amplifier Power Supply Bypassing/Filtering

Proper power supply bypassing is critical for low noise performance and high PSRR. Place the supply bypass capacitors as close to the device as possible. Typical applications employ a voltage regulator with $10\mu F$ and $0.1\mu F$ bypass capacitors that increase supply stability. These capacitors do not eliminate the need for bypassing of the LM48312 supply pins. A $1\mu F$ capacitor is recommended.

Audio Amplifier Input Capacitor Selection

Input capacitors may be required for some applications, or when the audio source is single-ended. Input capacitors block the DC component of the audio signal, eliminating any conflict between the DC component of the audio source and the bias voltage of the LM48312. The input capacitors create a high-pass filter with the input resistors $R_{\rm IN}$. The -3dB point of the high pass filter is found using Equation 1 below.

$$f = 1 / 2\pi R_{\rm IN} C_{\rm IN} \tag{1}$$

Where R_{IN} is the value of the input resistor given in the *Electrical Characteristics* table.

The input capacitors can also be used to remove low frequency content from the audio signal. Small speakers cannot reproduce, and may even be damaged by low frequencies. High pass filtering the audio signal helps protect the speakers. When the LM48312 is using a single-ended source, power supply noise on the ground is seen as an input signal. Setting the high-pass filter point above the power supply noise frequencies, 217Hz in a GSM phone, for example, filters out the noise such that it is not amplified and heard on the output. Capacitors with a tolerance of 10% or better are recommended for impedance matching and improved CMRR and PSRR.

Single-Ended Audio Amplifier Configuration

The LM48312 is compatible with single-ended sources. When configured for single-ended inputs, input capacitors must be used to block and DC component at the input of the device. Figure 39 shows the typical single-ended applications circuit.



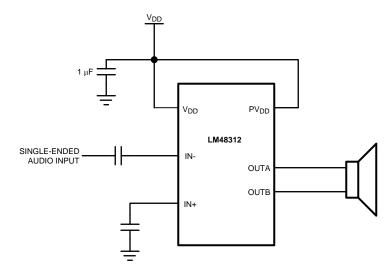


Figure 39. Single-Ended Input Configuration

PCB LAYOUT GUIDELINES

As output power increases, interconnect resistance (PCB traces and wires) between the amplifier, load and power supply create a voltage drop. The voltage loss due to the traces between the LM48312 and the load results in lower output power and decreased efficiency. Higher trace resistance between the supply and the LM48312 has the same effect as a poorly regulated supply, increasing ripple on the supply line, and reducing peak output power. The effects of residual trace resistance increases as output current increases due to higher output power, decreased load impedance or both. To maintain the highest output voltage swing and corresponding peak output power, the PCB traces that connect the output pins to the load and the supply pins to the power supply should be as wide as possible to minimize trace resistance.

The use of power and ground planes will give the best THD+N performance. In addition to reducing trace resistance, the use of power planes creates parasitic capacitors that help to filter the power supply line.

The inductive nature of the transducer load can also result in overshoot on one of both edges, clamped by the parasitic diodes to GND and V_{DD} in each case. From an EMI standpoint, this is an aggressive waveform that can radiate or conduct to other components in the system and cause interference. In is essential to keep the power and output traces short and well shielded if possible. Use of ground planes beads and micros-strip layout techniques are all useful in preventing unwanted interference.

As the distance from the LM48312 and the speaker increases, the amount of EMI radiation increases due to the output wires or traces acting as antennas become more efficient with length. Ferrite chip inductors places close to the LM48312 outputs may be needed to reduce EMI radiation.



Demo Board Schematic

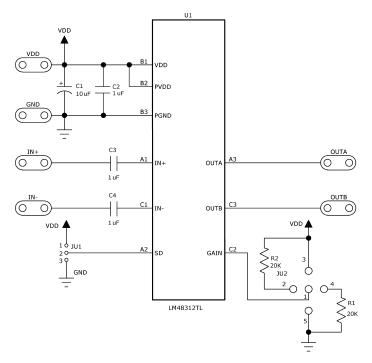


Figure 40. LM48312 Demoboard Schematic

LM48312TL Demoboard Bill of Materials

Designator	Quantity	Description
C1	1	10μF ±10% 16V Tantalum Capacitor (B Case) AVX TPSB106K016R0800
C2	1	1µF ±10% 16V X5R Ceramic Capacitor (603) Panasonic ECJ-1VB1C105K
C3, C4	2	1μF ±10% 16V X7R Ceramic Capacitor (1206) Panasonic ECJ-3YB1C105K
R1, R2	2	$20k\Omega \pm 5\%$ 1/10W Thick Film Resistor (603) Vishay CRCW060320R0JNEA
LM48312TL	1	LM48312TL (9-Bump DSBGA)



PC Board Layout

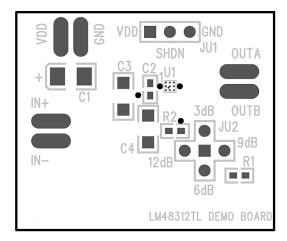


Figure 41. Top Silkscreen

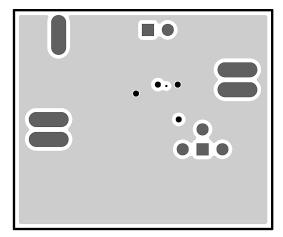


Figure 43. Layer 2 (GND)

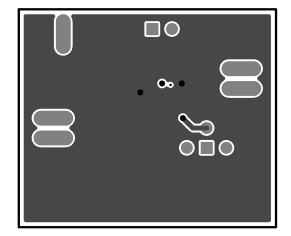


Figure 45. Bottom Layer

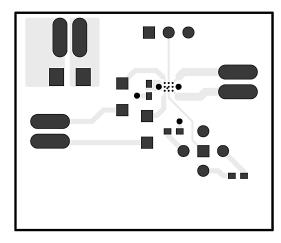


Figure 42. Top Layer

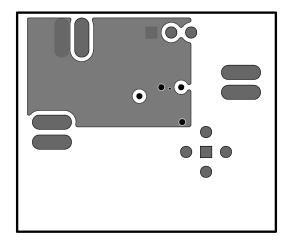


Figure 44. Layer 3 (V_{DD})

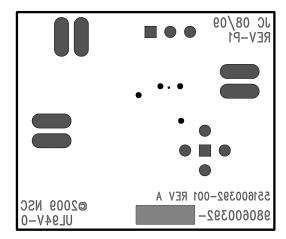


Figure 46. Bottom Silkscreen



REVISION HISTORY

Rev	Date	Description
1.0	01/20/10	Initial WEB released.
1.01	03/19/10	Text edits under the ENHANCED EMISSIONS section.
1.02	05/13/10	Edited Table 1.
1.03	07/25/12	Corrected the cover page (at WEB) (TI) from LM483127 to LM48312.

Changes from Revision C (May 2013) to Revision D				
•	Changed layout of National Data Sheet to TI format		16	

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PACKAGING INFORMATION

Orderable part number	Status	Material type	Package Pins	Package qty Carrier	RoHS	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
						(4)	(5)		
LM48312TLE/NOPB	Active	Production	DSBGA (YZR) 9	250 SMALL T&R	Yes	SNAGCU	Level-1-260C-UNLIM	-40 to 85	G N4
LM48312TLE/NOPB.A	Active	Production	DSBGA (YZR) 9	250 SMALL T&R	Yes	SNAGCU	Level-1-260C-UNLIM	-40 to 85	G N4
LM48312TLX/NOPB	Active	Production	DSBGA (YZR) 9	3000 LARGE T&R	Yes	SNAGCU	Level-1-260C-UNLIM	-40 to 85	G N4
LM48312TLX/NOPB.A	Active	Production	DSBGA (YZR) 9	3000 LARGE T&R	Yes	SNAGCU	Level-1-260C-UNLIM	-40 to 85	G N4

⁽¹⁾ Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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⁽²⁾ Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

⁽⁴⁾ Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.



PACKAGE OPTION ADDENDUM

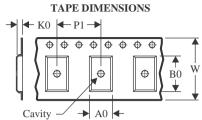
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PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

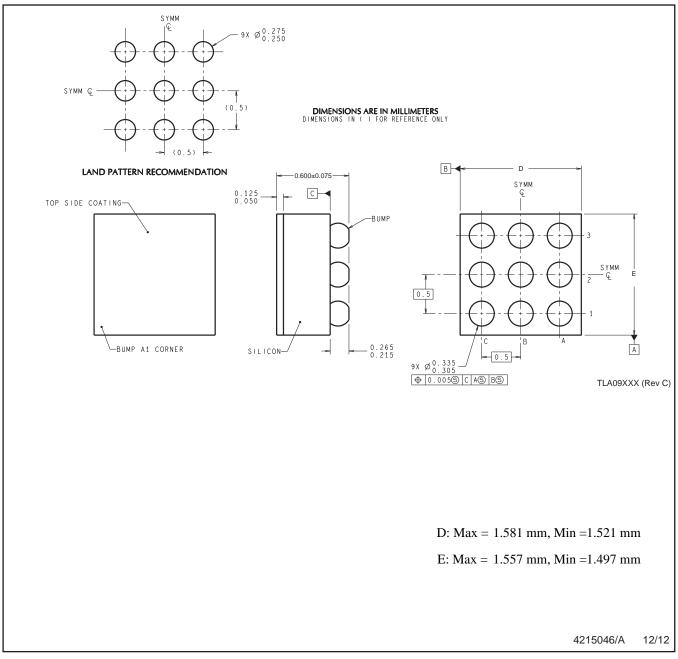
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LM48312TLE/NOPB	DSBGA	YZR	9	250	178.0	8.4	1.7	1.7	0.76	4.0	8.0	Q1
LM48312TLX/NOPB	DSBGA	YZR	9	3000	178.0	8.4	1.7	1.7	0.76	4.0	8.0	Q1

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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LM48312TLE/NOPB	DSBGA	YZR	9	250	208.0	191.0	35.0
LM48312TLX/NOPB	DSBGA	YZR	9	3000	208.0	191.0	35.0



NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.

B. This drawing is subject to change without notice.

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